

Note: *In this mode, the DIO14 cannot be used and it must be set as default (pull-down input). This is valid for the package QFN32 and WCSP34 only.*

3.21 SWD debug feature

The BlueNRG-2 embeds the ARM serial wire debug (SWD) port. It is two pins (clock and single bi-directional data) debug interface, providing all the debug functionality plus real-time access to system memory without halting the processor or requiring any target resident code.

Table 205. SWD port

Pin functionality	Pin name	Pin description
SWCLK	IO9	SWD clock signal
SWDIO	IO10	SWD data signal

The Cortex-M0 subsystem of the BlueNRG-2 embeds four breakpoints and two watchpoints.

3.21.1 Debugging tips

There are certain situations where debug access is disabled and the chip cannot be accessed, including:

- application that disables debug pins
- application that set the device in sleep or standby state, in which the debug port is not powered.

These cases are common during application development and device can end up in a state where debug access is no longer possible. To recover this situation, it is recommended to force IO7 pin high and hardware reset the device in order to force execution of the updater code (see [Section 3.23 Pre-programmed bootloader](#)). The user can then connect with SWD interface and erase the device Flash memory.

3.22 Bluetooth low energy radio

The BlueNRG-2 integrates an RF transceiver compliant to the Bluetooth specification and to the standard national regulations in the unlicensed 2.4 GHz ISM band.

The RF transceiver requires very few external discrete components. It provides 96 dB link budgets with excellent link reliability, keeping the maximum peak current below 15 mA.

In transmit mode, the power amplifier (PA) drives the signal generated by the frequency synthesizer out to the antenna terminal through a very simple external network. The power delivered as well as the harmonic content depends on the external impedance seen by the PA.

3.22.1 Radio operating modes

Several operating modes are defined for the BlueNRG-2 radio:

- Reset mode
- Sleep mode
- Active mode
- Radio mode
 - RX mode
 - TX mode

In Reset mode, the BlueNRG-2 is in ultra-low power consumption: all voltage regulators, clocks and the RF interface are not powered. The BlueNRG-2 enters Reset mode by asserting the external Reset signal. As soon as it is de-asserted, the device follows the normal activation sequence to transit to active mode.

In sleep mode either the low speed crystal oscillator or the low speed ring oscillator are running, whereas the high speed oscillators are powered down as well as the RF interface. The state of the BlueNRG-2 is retained and the content of the RAM is preserved.

While in sleep mode, the BlueNRG-2 waits until an internal timer expires and then it goes into active mode.

In active mode the BlueNRG-2 is fully operational: all interfaces, including RF, are active as well as all internal power supplies together with the high speed frequency oscillator. The MCU core is also running.

Radio mode differs from active mode as also the RF transceiver is active and it is capable of either transmitting or receiving.

3.23 Pre-programmed bootloader

BlueNRG-2 device has a pre-programmed bootloader supporting UART protocol with automatic baudrate detection. Main features of the embedded bootloader are:

- Auto baudrate detection up to 460 kbps
- Flash mass erase, section erase
- Flash programming
- Flash readout protection enable/disable

The pre-programmed bootloader is an application which is stored on the BlueNRG-2 internal ROM at manufacturing time by STMicroelectronics. This application allows upgrading the device Flash with a user application using a serial communication channel (UART).

Bootloader is activated by hardware by forcing IO7 high during power-up or hardware Reset, otherwise, application residing in Flash will be launched.

Note: The customer application must ensure that IO7 is forced low during power up. Bootloader protocol is described in a separate application note.

3.24 Unique device serial number

The BlueNRG-2 device has a unique six-byte serial number stored at address 0x100007F4: it is stored as two words (8 bytes) at addresses 0x100007F4 and 0x100007F8 with unique serial number padded with 0xAA55.

4 Pin description

The BlueNRG-2 comes in three package versions: WCSP34 offering 14 GPIOs, QFN32 offering 15 GPIOs and QFN48 offering 26 GPIOs. [Figure 22. BlueNRG-2 pin out top view \(QFN32\)](#) shows the QFN32 pin out, [Figure 23. BlueNRG-2 pin out top view \(QFN48\)](#) shows the QFN48 pin out and [Figure 24. BlueNRG-2 ball out top view \(WCSP34\)](#) shows the WCSP34 ball out.

Figure 21. BlueNRG-2 pin out top view (QFN32)

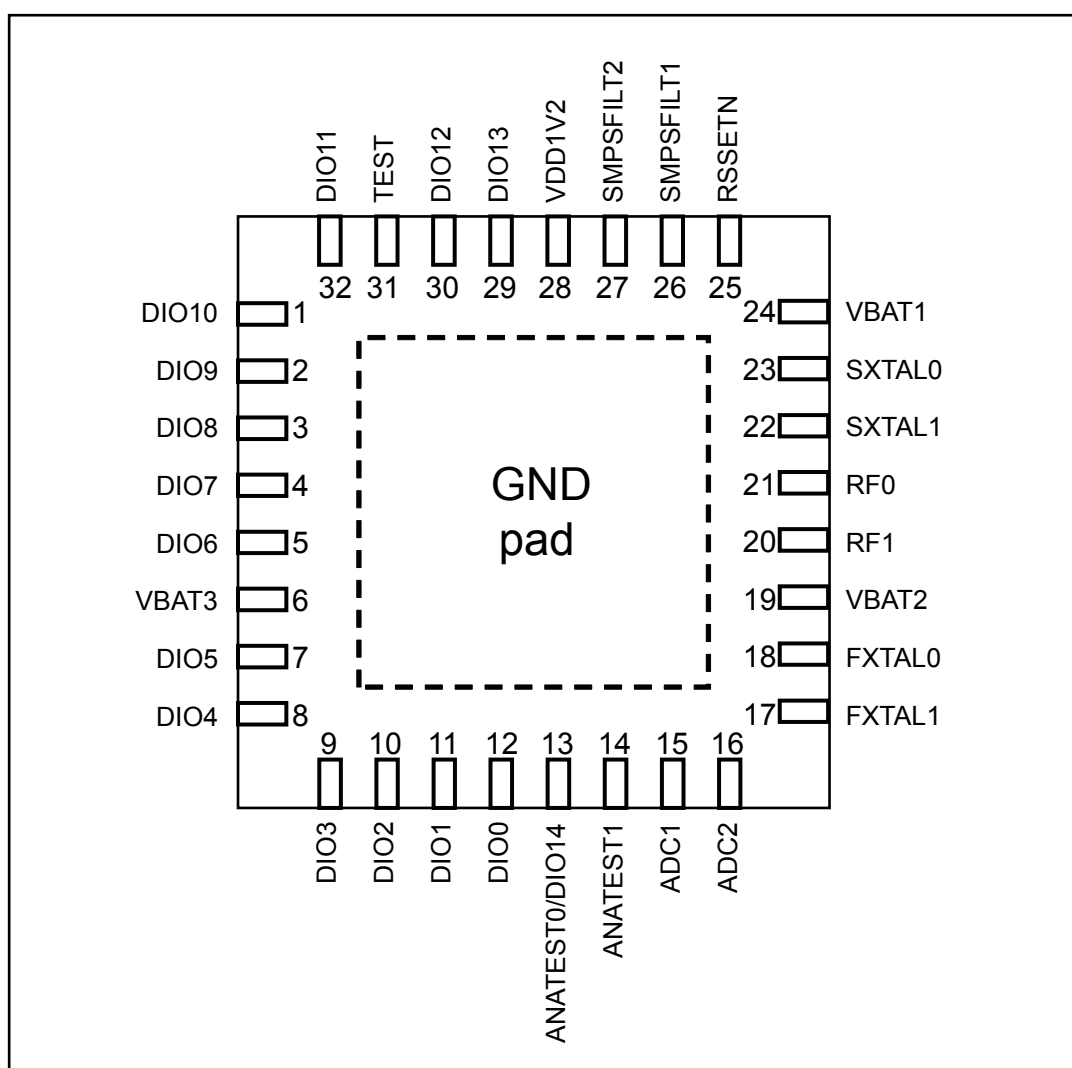


Figure 22. BlueNRG-2 pin out top view (QFN48)

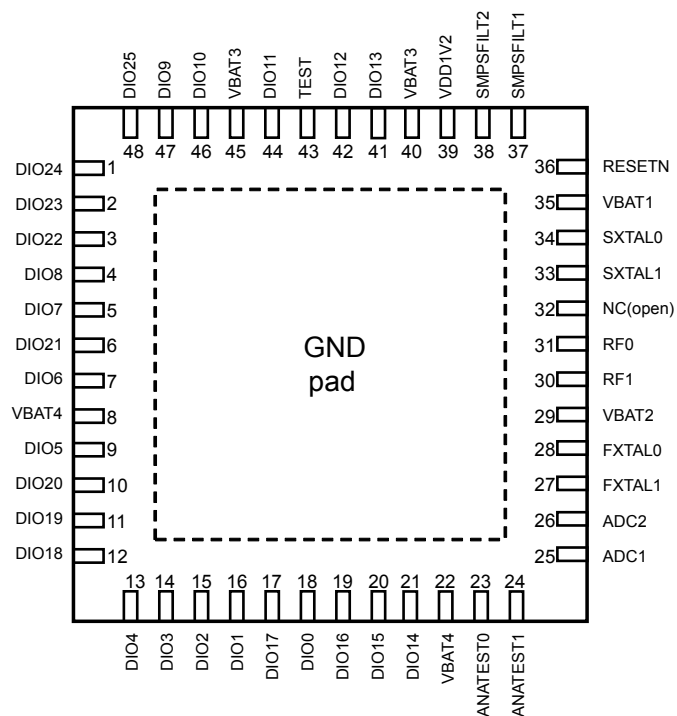


Figure 23. BlueNRG-2 ball out top view (WCSP34)

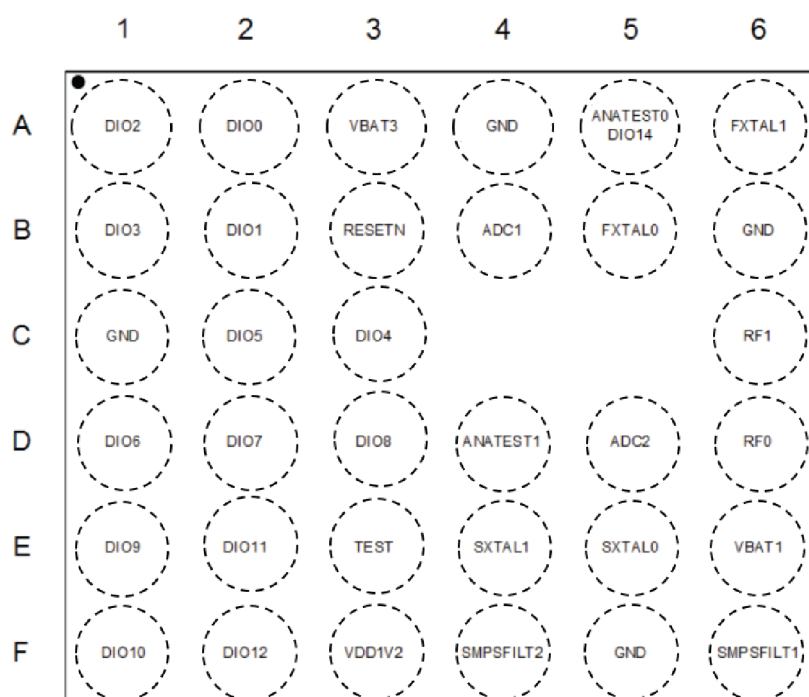
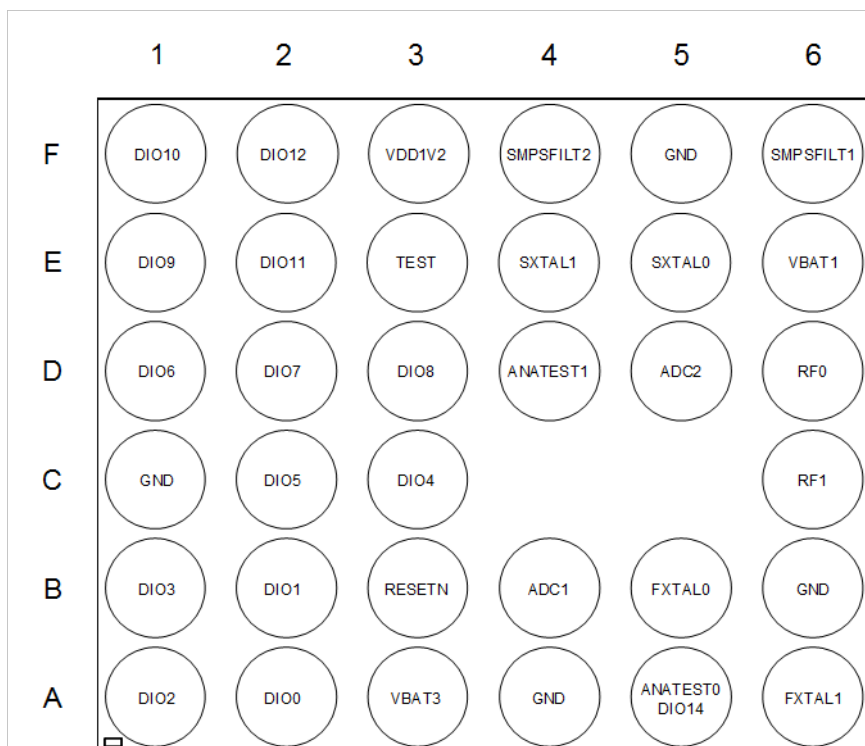


Figure 24. BlueNRG-2 ball out bottom view (WCSP34)

Table 206. Pinout description

Pins			Name	I/O	Description
QFN32	QFN48	WCSP34			
1	46	F1	DIO10	I/O	General purpose digital I/O
2	47	E1	DIO9	I/O	General purpose digital I/O
3	4	D3	DIO8	I/O	General purpose digital I/O
4	5	D2	DIO7/BOOT ⁽¹⁾	I/O	Bootloader pin/ General purpose digital I/O
5	7	D1	DIO6	I/O	General purpose digital I/O
6	40	A3	VBAT3	VDD	Battery voltage input
-	45	-			
7	9	C2	DIO5	I/O	General purpose digital I/O
8	13	C3	DIO4	I/O	General purpose digital I/O
9	14	B1	DIO3	I/O	General purpose digital I/O
10	15	A1	DIO2	I/O	General purpose digital I/O
11	16	B2	DIO1	I/O	General purpose digital I/O
12	18	A2	DIO0	I/O	General purpose digital I/O
13	21	A5	DIO14	I/O	General purpose digital I/O
	23		ANATEST0	O	Analog output

Pins			Name	I/O	Description
QFN32	QFN48	WCSP34			
14	24	D4	ANATEST1	O	Analog output
15	25	B4	ADC1	I	ADC input 1
16	26	D5	ADC2	I	ADC input 2
17	27	A6	FXTAL1	I	16/32 MHz crystal
18	28	B5	FXTAL0	I	16/32 MHz crystal
19	29	-	VBAT2	VDD	Battery voltage input
20	30	C6	RF1	I/O	Antenna + matching circuit connection
21	31	D6	RF0	I/O	Antenna + matching circuit connection
22	33	E4	SXTAL1	I	32 kHz crystal
23	34	E5	SXTAL0	I	32 kHz crystal
24	35	E6	VBAT1	VDD	Battery voltage input
25	36	B3	RESETN	I	System reset
26	37	F6	SMPSFILT1	I	SMPS output to external filter
27	38	F4	SMPSFILT2	I/O	SMPS output to external filter/battery voltage input
28	39	F3	VDD1V2	O	1.2V digital core output
29	41	-	DIO13	I/O	General purpose digital I/O
30	42	F2	DIO12	I/O	General purpose digital I/O
31	43	E3	TEST	I	Test pin put to GND
32	44	E2	DIO11	I/O	General purpose digital I/O
-	-	A4	GND	GND	Ground
-	-	B6			
-	-	C1			
-	-	F5			
-	20	-	DIO15	I/O	General purpose digital I/O
-	19	-	DIO16	I/O	General purpose digital I/O
-	17	-	DIO17	I/O	General purpose digital I/O
-	12	-	DIO18	I/O	General purpose digital I/O
-	11	-	DIO19	I/O	General Purpose Digital I/O
-	10	-	DIO20	I/O	General purpose digital I/O
-	6	-	DIO21	I/O	General Purpose Digital I/O
-	3	-	DIO22	I/O	General purpose digital I/O
-	2	-	DIO23	I/O	General purpose digital I/O
-	1	-	DIO24	I/O	General purpose digital I/O
-	8	-	VBAT4	VDD	Battery voltage input
-	22	-			
-	32	-	Not connected	-	-
-	48	-	DIO25	I/O	General purpose digital I/O

1. The pin IO7/BOOT is monitored by bootloader after power-up or hardware reset and it should be low to prevent unwanted bootloader activation.

5 Memory mapping

Program memory, data memory, registers and I/O ports are organized within the same linear 4-Gbyte address space.

The bytes are coded in memory in little Endian format. The lowest numbered byte in a word is considered the word's least significant byte and highest numbered byte the most significant.

The addressable memory space is divided into 16 main blocks, each 256 MB. All the memory areas that are not allocated to on-chip memories and peripherals are considered "RESERVED".

For the detailed mapping of an available memory and register areas, please refer to the memory map in table below and to the register lists detailed in each of the peripheral sections.

Table 207. Memory mapping

Address	Cortex-M0 address map	Size	Description
0x0000_0000 – 0x0000_07FF	Code	2 kB	ROM
0x1000_0000 – 0x1000_07FF	Code	2 kB	ROM
0x1004_0000 – 0x1007_FFFF	Code	256 kB	Flash
0x2000_0000 – 0x2000_2FFF ⁽¹⁾	SRAM0 always on	12 kB	SRAM
0x2000_3000 – 0x2000_5FFF	SRAM1 switchable	12 kB	SRAM
0x2000_6000 – 0x3FFF_FFFF			RESERVED
0x4000_0000	APB peripheral	4 kB	GPIO
0x4010_0000		4 kB	Flash controller
0x4020_0000		4 kB	System controller
0x4030_0000		4 kB	UART
0x4040_0000		4 kB	SPI
0x4050_0000		4 kB	RESERVED
0x4060_0000		4 kB	RESERVED
0x4070_0000		4 kB	Watchdog
0x4080_0000		4 kB	ADC
0x4090_0000		4 kB	Clock generator
0x40A0_0000		4 kB	I2C2
0x40B0_0000		4 kB	I2C1 ⁽²⁾
0x40C0_0000		4 kB	AHB up converter
0x40D0_0000		4 kB	MFT1
0x40E0_0000		4 kB	MFT2
0x40F0_0000		4 kB	RTC
0x4100_0000		4 kB	RESERVED
0x4800_0000		4 kB	BLE controller
0x4810_0000		4 kB	BLE clock generator
0x5000_0000	AHB peripheral	4 kB	RESERVED
0xA000_0000		4 kB	DMA controller
0xB000_0000		4 kB	RNG
0xC000_0000		4 kB	PKA

Address	Cortex-M0 address map	Size	Description
0xC000_0400	AHB peripheral	1 kB	PKA RAM
0xE000_0000 – 0xE00F_FFFF	Private peripheral bus	1 MB	Cortex-M0 registers
0xE010_0000 – 0xEFFF_FFFF	RESERVED	256 MB	RESERVED
0xF000_0000 – 0xFFFF_FFFF		256 MB	RESERVED

1. 0x200000C0-0x200002CB reserved for radio controller.

2. The I²C 1 is not available in WLCSP34 package.

All the peripherals are addressed by APB, except DMA, RNG and PKA peripherals that are addressed by AHB. The peripherals DMA, RNG and PKA that are addressed through the AHB, must be accessed only with 32-bit accesses. Any 8-bit or 16-bit access generates an AHB error leading to a hard fault on Cortex-M0.

6 Application circuit

The schematics below are purely indicative.

Figure 25. Application circuit: active DC-DC converter QFN32 package

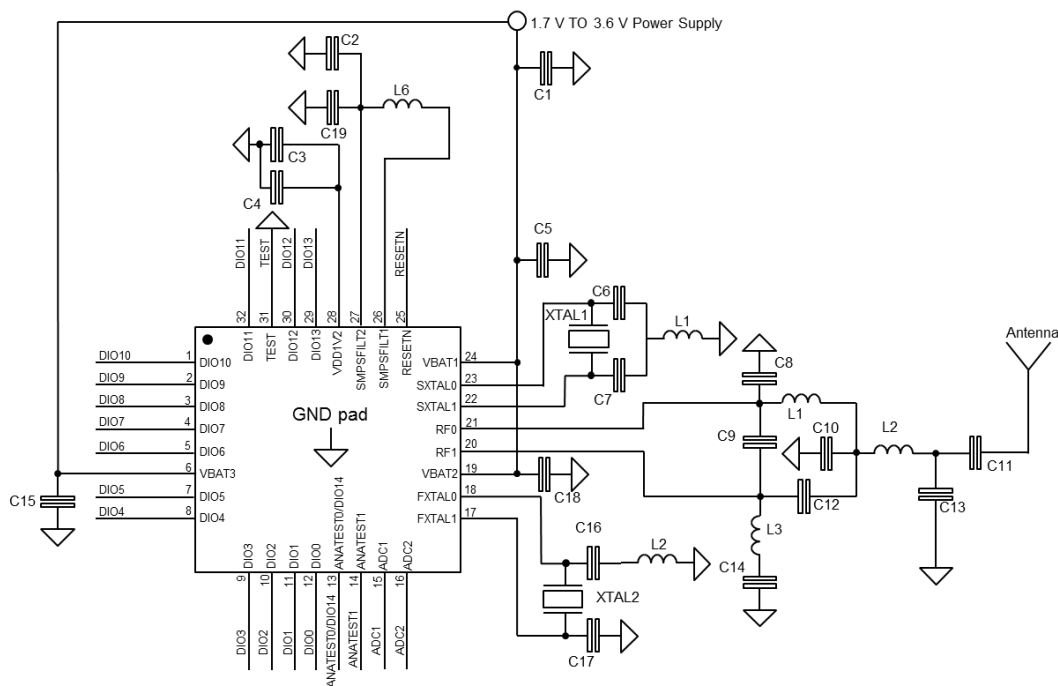
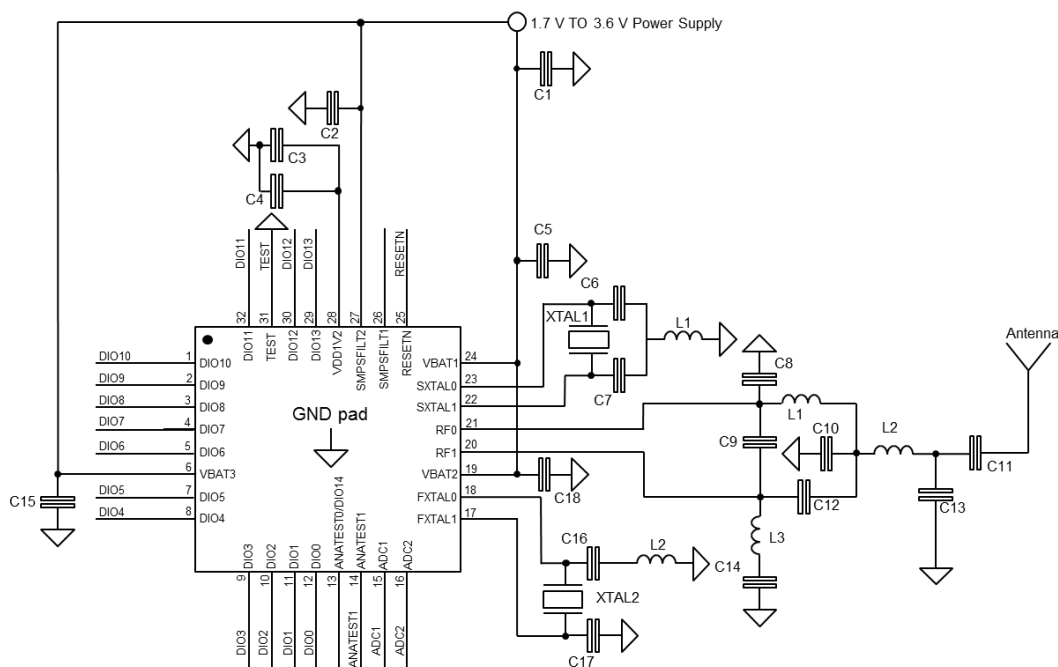


Figure 26. Application circuit: non-active DC-DC converter QFN32 package



[illegible]

Figure 29. Application circuit: active DC-DC converter QFN32 package with BALF-NRG-02D3 balun

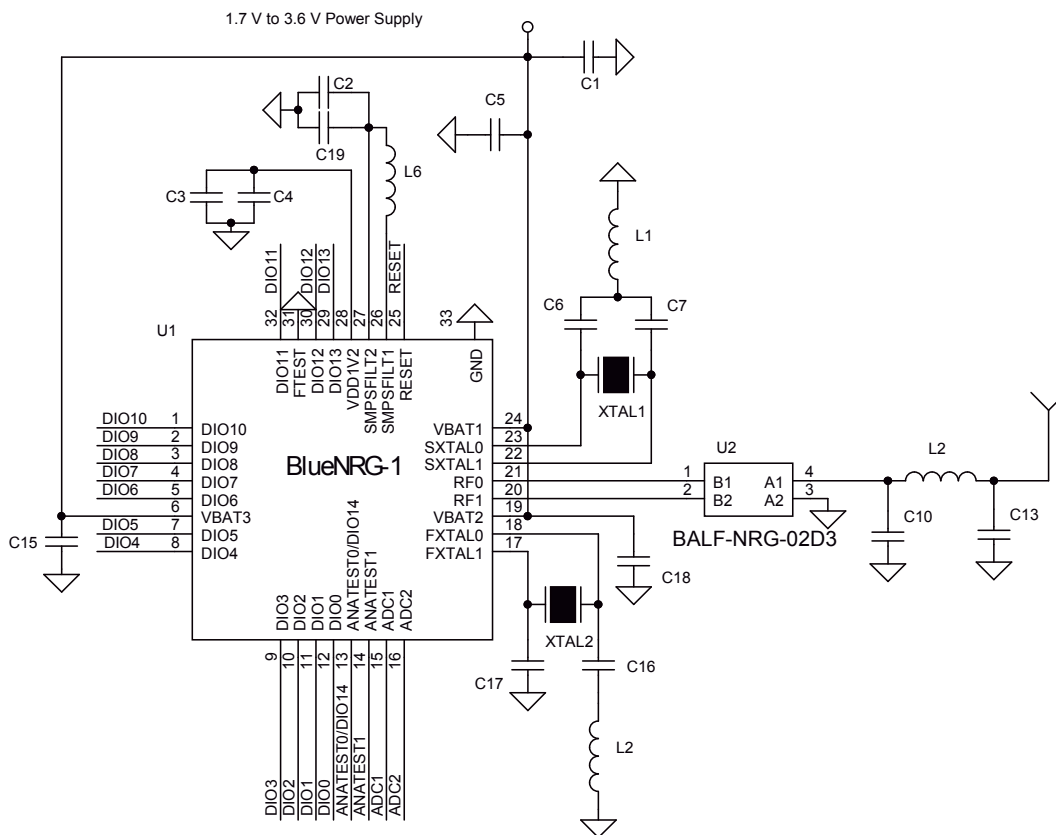


Table 208. External component list

Component	Description
C1	Decoupling capacitor
C2	DC-DC converter output capacitor
C3	Decoupling capacitor for 1.2 V digital regulator
C4	Decoupling capacitor for 1.2 V digital regulator
C5	Decoupling capacitor
C6	32 kHz crystal loading capacitor
C7	32 kHz crystal loading capacitor
C8	RF balun/matching network capacitor
C9	RF balun/matching network capacitor
C10	RF balun/matching network capacitor
C11	RF balun/matching network capacitor
C12	RF balun/matching network capacitor
C13	RF balun/matching network capacitor
C14	RF balun/matching network capacitor
C15	Decoupling capacitor
C16	16/32 MHz crystal loading capacitor
C17	16/32 MHz crystal loading capacitor

Component	Description
C18	Decoupling capacitor
C19	DC-DC converter output capacitor
L1	32 kHz crystal filter inductor
L2	16/32 MHz crystal filter inductor
L3	RF balun/matching network inductor
L4	RF balun/matching network inductor
L5	RF balun/matching network inductor
XTAL1	32 kHz crystal (optional)
XTAL2	16/32 MHz crystal

7 Absolute maximum ratings and thermal data

Table 209. Absolute maximum ratings

Pin	Parameter	Value	Unit
VBAT3, VBAT2, VBAT1, RESETN, SMPSFILT1, SMPSFILT2	DC-DC converter supply voltage input and output	-0.3 to +3.9	V
VDD1V2	DC voltage on linear voltage regulator	-0.3 to +1.3	V
DIO0 to DIO25, TEST	DC voltage on digital input/output pins	-0.3 to +3.9	V
ANATEST0, ANATEST1, ADC1, ADC2	DC voltage on analog pins	-0.3 to +3.9	V
FXTAL0, FXTAL1, SXTAL0, SXTAL1	DC voltage on XTAL pins	-0.3 to +1.4	V
RF0, RF1	DC voltage on RF pins	-0.3 to +1.4	V
TSTG	Storage temperature range	-40 to +125	°C
VESD-HBM	Electrostatic discharge voltage	±2.0	kV

Note: Absolute maximum ratings are those values above which damage to the device may occur. Functional operation under these conditions is not implied. All voltages are referred to GND.

Table 210. Thermal data

Symbol	Parameter	Value	Unit
Rthj-amb	Thermal resistance junction-ambient	34 (QFN32) 50 (WLCSP34)	°C/W
Rthj-c	Thermal resistance junction-case	2.5 (QFN32) 25 (WLCSP34)	°C/W

8 General characteristics

Table 211. Operating conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{BAT}	Operating battery supply voltage	1.7		3.6	V
T _A	Operating Ambient temperature range	-40		+105	°C

9 Electrical specifications

9.1 Electrical characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BAT} = 3.0\text{ V}$. All performance data are referred to a $50\text{ }\Omega$ antenna connector, via reference design, QFN32 package version.

Table 212. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Power consumption when DC-DC converter active						
I _{BAT}	Supply current	Reset	–	5	–	nA
		Standby	–	500	–	nA
		Sleep mode: 32 kHz XO ON (24 KB retention RAM)	–	0.9	–	μA
		Sleep mode: 32 kHz RO ON (24 KB retention RAM)		2.1		
		Active mode: CPU, Flash and RAM on	–	1.9	–	mA
		RX	–	7.7	–	mA
		TX +8 dBm	–	15.1	–	mA
		TX +4 dBm		10.9		
		TX +2 dBm		9		
		TX -2 dBm		8.3		
		TX -5 dBm		7.7		
		TX -8 dBm		7.1		
		TX -11 dBm		6.8		
		TX -14 dBm		6.6		
Power consumption when DC-DC converter not active						
I _{BAT}	Supply current	Reset	–	5	–	nA
		Standby	–	500	–	nA
		Sleep mode: 32 kHz XO ON (24 KB retention RAM)	–	0.9	–	μA
		Sleep mode: 32 kHz RO ON (24 KB retention RAM)	–	2.1	–	
		Active mode: CPU, Flash and RAM on	–	3.3	–	mA
I _{BAT}	Supply current	RX	–	14.5	–	mA
		TX +8 dBm	–	28.8		mA
		TX +4 dBm		20.5		
		TX +2 dBm		17.2		
		TX -2 dBm		15.3		
		TX -5 dBm		14		
		TX -8 dBm		13		
		TX -11 dBm		12.3		
		TX -14 dBm		12		

Table 213. Digital I/O specifications

Symbol	Test conditions	Min.	Typ.	Max.	Unit
T(RST)L			1.5		ms
TC			3.3		V
TC1			2.5		V
TC2			1.8		V
VIL				0.3*VDD	V
VIH		0.65*VDD			V
VOL	IOL = 3 mA			0.4	V
VOH	IOH = 3 mA	0.7*VDD			V
IOL (low drive strength)	TC (VOL = 0.4 V)		5.6		mA
	TC1 (VOL = 0.42 V)		6.6		mA
	TC2 (VOL = 0.45 V)		3		mA
IOL (high drive strength)	TC (VOL = 0.4 V)		11.2		mA
	TC1 (VOL = 0.42 V)		13.2		mA
	TC2 (VOL = 0.45 V)		6		mA
IOL (Very high drive strength)	TC (VOL = 0.4 V)		16.9		mA
	TC1 (VOL = 0.42 V)		19.9		mA
	TC2 (VOL = 0.45 V)		9.2		mA
IOH (low drive strength)	TC (VOH = 2.4 V)		10.6		mA
	TC1 (VOH = 1.72 V)		7.2		mA
	TC2 (VOH = 1.35 V)		3		mA
IOH (high drive strength)	TC (VOH = 2.4 V)		19.2		mA
	TC1 (VOH = 1.72 V)		12.9		mA
	TC2 (VOH = 1.35 V)		5.5		mA
IOH (very high drive strength)	TC (VOH = 2.4 V)		29.4		mA
	TC1 (VOH = 1.72 V)		19.8		mA
	TC2 (VOH = 1.35 V)		8.4		mA
IPUD (current sourced/sunk from IOs with pull enabled)	Static supply 1.7 V	5		10	μA
	Static supply 3.6 V	40		60	μA

9.1.1 Peripheral current consumption

Table 214. Peripheral current consumption

Peripheral	Typical consumption V _{DD} = 3.0 V, T _A = 25 °C	Unit
GPIO	11.0	μA
Flash controller	6.0	
System controller	0.75	
UART	77.0	
SPI	41.0	
Watchdog	4.0	

Peripheral	Typical consumption $V_{DD} = 3.0\text{ V}$, $T_A = 25\text{ °C}$	Unit
ADC	5.0	μA
I2C1	92.0	
I2C2	92.0	
MFT1	7.5	
MFT2	7.5	
RTC	7.5	
DMA	16.5	
RNG	25.0	
PKA	26.0	

Note: The values are calculated as the increment to the current consumption when the peripheral is activated. The peripheral is activated if the related clock is provided.

9.2 RF general characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ °C}$, $V_{BAT} = 3.0\text{ V}$. All performance data are referred to a $50\text{ }\Omega$ antenna connector, via reference design, QFN32 package version.

Table 215. RF general characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
FREQ	Frequency range		2400	–	2483.5	MHz
FCH	Channel spacing		–	2	–	MHz
RFch	RF channel center frequency		2402	–	2480	MHz

9.3 RF transmitter characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ °C}$, $V_{BAT} = 3.0\text{ V}$. All performance data are referred to a $50\text{ }\Omega$ antenna connector, via reference design, QFN32 package version.

Table 216. RF transmitter characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
MOD	Modulation scheme		GFSK			
BT	Bandwidth-bit period product		–	0.5	–	
Mindex	Modulation index		–	0.5	–	
DR	Air data rate		–	1	–	Mbps
PMAX	Maximum output power	At antenna connector	–	+8	+10	dBm
PRFC	Minimum output power		–	-16.5	–	dBm
PBW1M	6 dB bandwidth for modulated carrier (1 Mbps)	Using resolution bandwidth of 100 kHz	500	–	–	kHz
PRF1	1 st adjacent channel transmit power 2 MHz	Using resolution bandwidth of 100 kHz and average detector	–	-35	–	dBm

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
PRF2	2 nd Adjacent channel transmit power >3 MHz	Using resolution bandwidth of 100 kHz and average detector	–	–40	–	dBm
ZLOAD	Optimum differential load	@ 2440 MHz	–	25.4 + j20.8 ⁽¹⁾	–	Ω

1. Simulated value.

9.4 RF receiver characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ °C}$, $V_{BAT} = 3.0\text{ V}$. All performance data are referred to a $50\text{ }\Omega$ antenna connector, via reference design, QFN32 package version.

Table 217. RF receiver characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
RXSENS	Sensitivity	BER <0.1%		–88		dBm
PSAT	Saturation	BER <0.1%		11		dBm
zIN	Input differential impedance	@ 2440 MHz		25.5-j14.2		Ω
RF selectivity with BLE equal modulation on interfering signal						
C/ICO-channel	Co-channel interference	Wanted signal = –67 dBm, BER ≤ 0.1%		6		dBc
C/I1 MHz	Adjacent (+1 MHz) interference	Wanted signal = –67 dBm, BER ≤ 0.1%		0		dBc
C/I2 MHz	Adjacent (+2 MHz) interference	Wanted signal = –67 dBm, BER ≤ 0.1%		–40		dBc
C/I3 MHz	Adjacent (+3 MHz) interference	Wanted signal = –67 dBm, BER ≤ 0.1%		–47		dBc
C/I≥4 MHz	Adjacent (≥ ± 4 MHz) interference	Wanted signal = –67 dBm, BER ≤ 0.1%		–46		dBc
C/I≥6 MHz	Adjacent (≥ ± 6 MHz) interference	Wanted signal = –67 dBm, BER ≤ 0.1%		–48		dBc
C/I≥25 MHz	Adjacent (≥ ±25 MHz) interference	Wanted signal = –67 dBm, BER ≤ 0.1%		–70		dBc
C/IImage	Image frequency interference –2 MHz	Wanted signal = –67 dBm, BER ≤ 0.1%		–16		dBc
C/IImage±1 MHz	Adjacent (±1 MHz) interference to in-band image frequency –1 MHz –3 MHz	Wanted signal = –67 dBm, BER ≤ 0.1%		0 –23		dBc
Intermodulation characteristics (CW signal at f_1, BLE interfering signal at f_2)						
P_IM(3)	Input power of IM interferes at 3 and 6 MHz distance from wanted signal	Wanted signal = –64 dBm, BER ≤ 0.1%		–34		dBm
P_IM(–3)	Input power of IM interferes at –3 and –6 MHz distance from wanted signal	Wanted signal = –64 dBm, BER ≤ 0.1%		–48		dBm
P_IM(4)	Input power of IM interferes at ±4 and ±8 MHz distance from wanted signal	Wanted signal = –64 dBm, BER ≤ 0.1%		–34		dBm
P_IM(5)	Input power of IM interferes at ±5 and ±10 MHz distance from wanted signal	Wanted signal = –64 dBm, BER ≤ 0.1%		–34		dBm

9.5 High speed crystal oscillator characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BAT} = 3.0\text{ V}$.

Table 218. High speed crystal oscillator characteristics

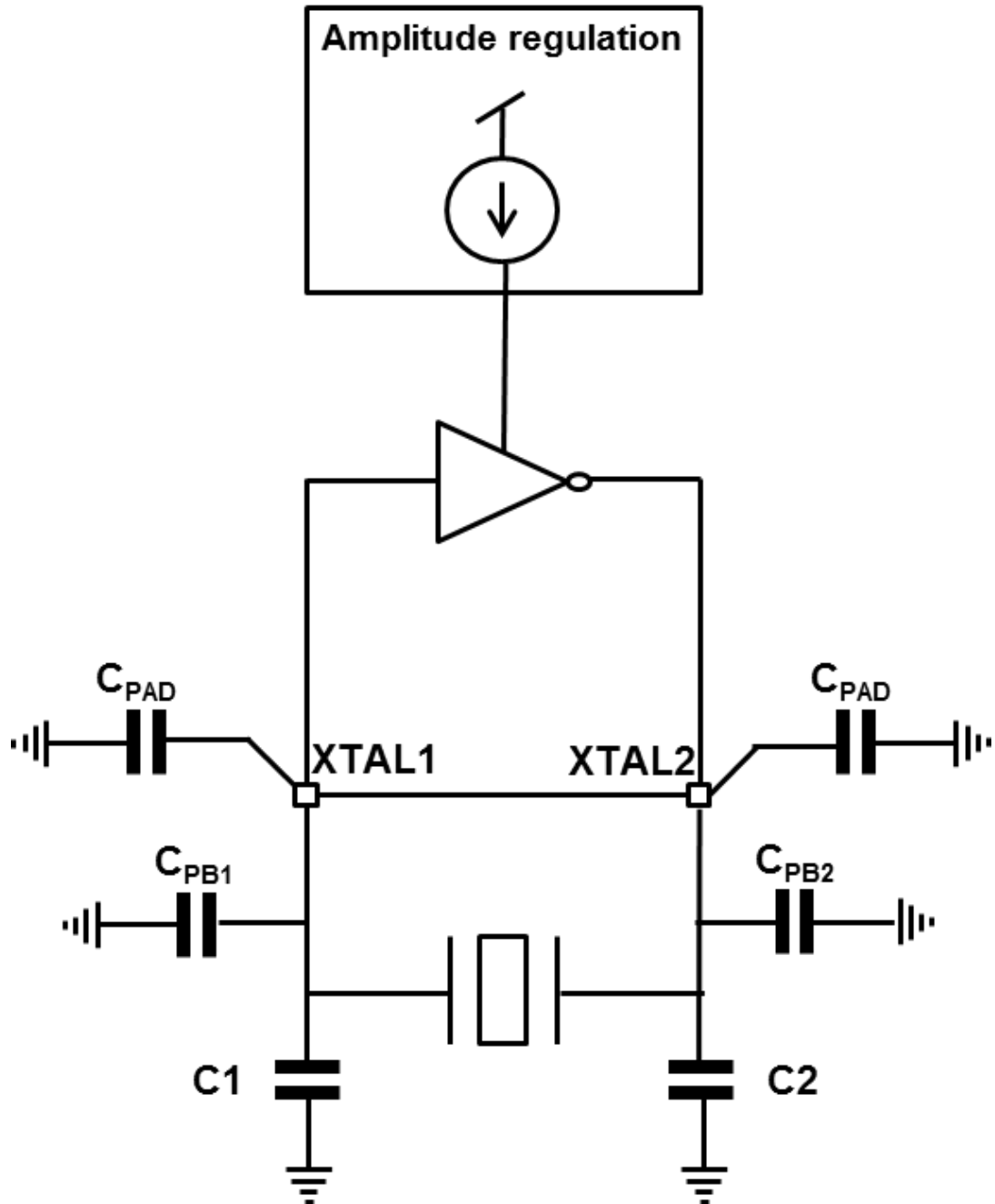
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
fNOM	Nominal frequency		–	16/32	–	MHz
fTOL	Frequency tolerance	Includes initial accuracy, stability over temperature, aging and frequency pulling due to incorrect load capacitance	–	–	±50	ppm
ESR	Equivalent series resistance		–	–	100	Ω
PD	Drive level		–	–	100	μW

9.5.1 High speed crystal oscillator

The BlueNRG-2 includes a fully integrated low power 16/32 MHz Xtal oscillator with an embedded amplitude regulation loop. In order to achieve low power operation and good frequency stability of the XTAL oscillator, certain considerations with respect to the quartz load capacitance C_0 need to be taken into account.

Figure 31. High speed oscillator block diagram shows a simplified block diagram of the amplitude regulated oscillator used on the BlueNRG-2.

Figure 30. High speed oscillator block diagram



Low power consumption and fast startup time is achieved by choosing a quartz crystal with a low load capacitance C_0 . A reasonable choice for capacitor C_0 is 12 pF. To achieve good frequency stability, the following equation needs to be satisfied:

$$C_0 = \frac{C_1' \cdot C_2'}{C_1 + C_2} \quad (6)$$

Where $C_1' = C_1 + C_{PCB1} + C_{PAD}$, $C_2' = C_2 + C_{PCB2} + C_{PAD}$, where C_1 and C_2 are external (SMD) components, C_{PCB1} and C_{PCB2} are PCB routing parasites and C_{PAD} is the equivalent small-signal pad-capacitance. The value of C_{PAD} is around 0.5 pF for each pad. The routing parasites should be minimized by placing quartz and C_1/C_2 capacitors close to the chip, not only for an easier matching of the load capacitance C_0 , but also to ensure robustness against noise injection. Connect each capacitor of the Xtal oscillator to ground by a separate vias.

9.6 Low speed crystal oscillator characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BAT} = 3.0\text{ V}$.

Table 219. Low speed crystal oscillator characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
f _{NOM}	Nominal frequency		–	32.768	–	kHz
f _{TOL}	Frequency tolerance	Includes initial accuracy, stability over temperature, aging and frequency pulling due to incorrect load capacitance.	–	–	±50	ppm
ESR	Equivalent series resistance		–	–	90	kΩ
PD	Drive level		–	–	0.1	μW

Note: These values are the correct ones for NX3215SA-32.768 kHz-EXS00A-MU00003.

9.7 High speed ring oscillator characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BAT} = 3.0\text{ V}$.

Table 220. High speed ring oscillator characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
f _{NOM}	Nominal frequency		–	14	–	MHz

9.8 Low speed ring oscillator characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BAT} = 3.0\text{ V}$, QFN32 package version.

Table 221. Low speed ring oscillator characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
32 kHz ring oscillator (LSROSC)						
f _{NOM}	Nominal frequency		–	32	–	kHz

9.9 N-fractional frequency synthesizer characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical value are referred to $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BAT} = 3.0\text{ V}$, $f_c = 2440\text{ MHz}$.

Table 222. N-Fractional frequency synthesizer characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
PNSYNTH	RF carrier phase noise	At ±1 MHz offset from carrier	–	-113	–	dBc/Hz
		At ±3 MHz offset from carrier	–	-119	–	dBc/Hz
LOCKTIME	PLL lock time		–	–	40	μs
TOTIME	PLL turn-on / hop time	Including calibration	–	–	150	μs

9.10 Auxiliary block characteristics

Characteristics measured over recommended operating conditions unless otherwise specified. Typical values are referenced to $T_A = 25\text{ }^{\circ}\text{C}$, $V_{BAT} = 3.0\text{ V}$, $f_{\text{ADCclk}} = 1\text{ MHz}$. QFN32 package version.

Table 223. Auxiliary block characteristics

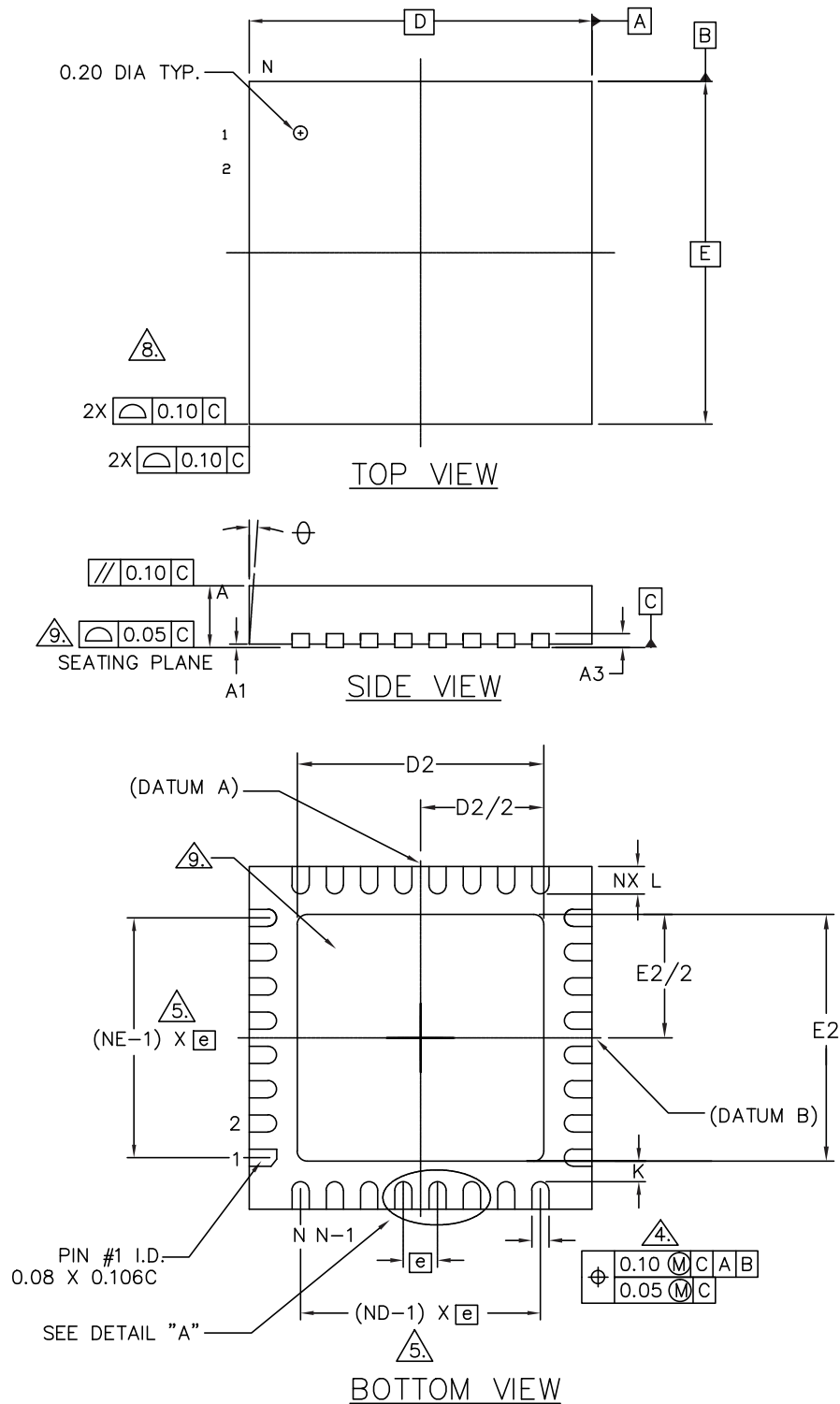
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Analog-to-digital converter (ADC)						
V_{DDA}	Analog supply voltage		1.7	3.0	3.6	V
$I_{DDA, \text{AVG}}$	Analog supply current	Average current during conversion	–	–	0.55	mA
$V_{\text{INP}, \text{INN}}$	Input pin voltage	With input attenuator	-50 mV	–	$(V_{BAT} + 50\text{ mV}) / \text{input attenuation}$	V
SNR Diff	Signal-to-noise ratio	Differential input, with $\text{OSR} = 200$, $\text{PGA} = 0\text{ dB}$. Sinewave with $V_{\text{inDC}} = 0.6\text{ V}$, $V_{\text{peak diff}} = 0.85\text{ V}$, $F_{\text{in}} = 1\text{ kHz}$	–	74	–	dB
SNR SE 1	Signal-to-noise ratio	Single-ended input, with $V_{\text{REF}} = 0.6\text{ V}$, $\text{OSR} = 200$, $\text{PGA} = 0\text{ dB}$. Sinewave with $V_{\text{inDC}} = 0.6\text{ V}$, $V_{\text{peak}} = 0.425\text{ V}$, $F_{\text{in}} = 1\text{ kHz}$	–	70	–	dB
ENOB Diff	Effective number of bits	Differential input, $\text{OSR} = 200$, $\text{PGA} = 0\text{ dB}$. Sinewave with $V_{\text{inDC}} = 0.6\text{ V}$, $V_{\text{peak diff}} = 0.85\text{ V}$, $F_{\text{in}} = 1\text{ kHz}$	–	12	–	bit
ENOB SE 1a	Effective number of bits	Single-ended input, with $V_{\text{REF}} = 0.6\text{ V}$, with $\text{OSR} = 200$, $\text{PGA} = 0\text{ dB}$. Sinewave with $V_{\text{inDC}} = 0.6\text{ V}$, $V_{\text{peak}} = 0.425\text{ V}$, $F_{\text{in}} = 1\text{ kHz}$	–	8.5	–	bit
ENOB SE 1b	Effective number of bits	Single-ended input, with $V_{\text{REF}} = 0.6\text{ V}$, $\text{OSR} = 200$, $\text{PGA} = 0\text{ dB}$. Sinewave with $V_{\text{inDC}} = 0.6\text{ V}$, $V_{\text{peak}} = 0.15\text{ V}$, $F_{\text{in}} = 1\text{ kHz}$	–	9.5	–	bit
Analog temperature sensor						
TRANGE	Temperature range		-40	–	+105	$^{\circ}\text{C}$
TERR	Error in temperature		-4	0	+4	$^{\circ}\text{C}$
Battery sensor						
VBLTRANGE	Battery level indicator range		1.8		3.6	V
VBLTERR	Battery level indicator error	After calibration	-150		150	mV
Brown-out reset (BOR)						
VABOR	Ascending brown-out threshold		–	1.68	1.7	V
VDBOR	Descending brown-out threshold		1.62	1.645	–	V

10 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

10.1 QFN32 package information

Figure 31. QFN32 (5 x 5 x 1 pitch 0.5 mm) package outline

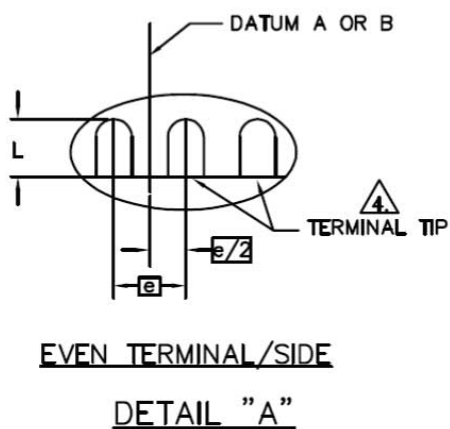


QFN32_POA_8362854_B

Table 224. QFN32 (5 x 5 x 1 pitch 0.5 mm) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80	0.85	1.00
A1	0	0.02	0.05
A3	0.20 REF		
b	0.18	0.25	0.30
D	5.00 BSC		
E	5.00 BSC		
D2	3.2		3.70
E2	3.2		3.70
e	0.5 BSC		
L	0.30	0.40	0.50
Φ	0°		14°
K	0.20		

Figure 32. QFN32 (5 x 5 x 1 pitch 0.5 mm) package detail "A"



10.2 QFN48 package information

Figure 33. QFN48 (|6 x 6 x 0.85 pitch 0.4 mm) package outline

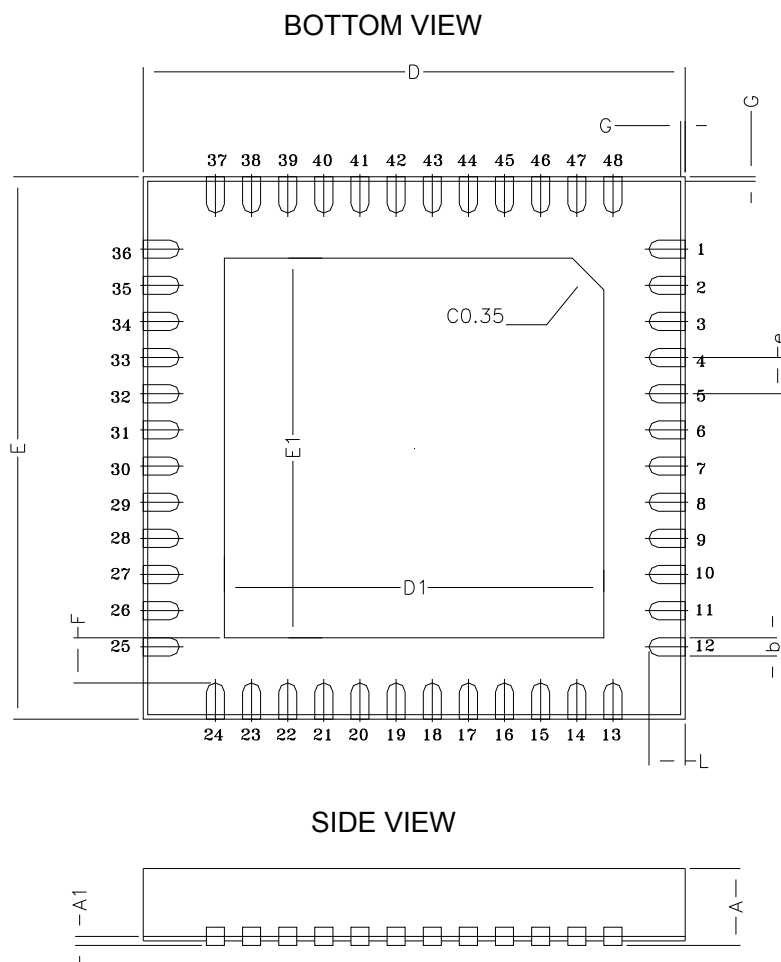


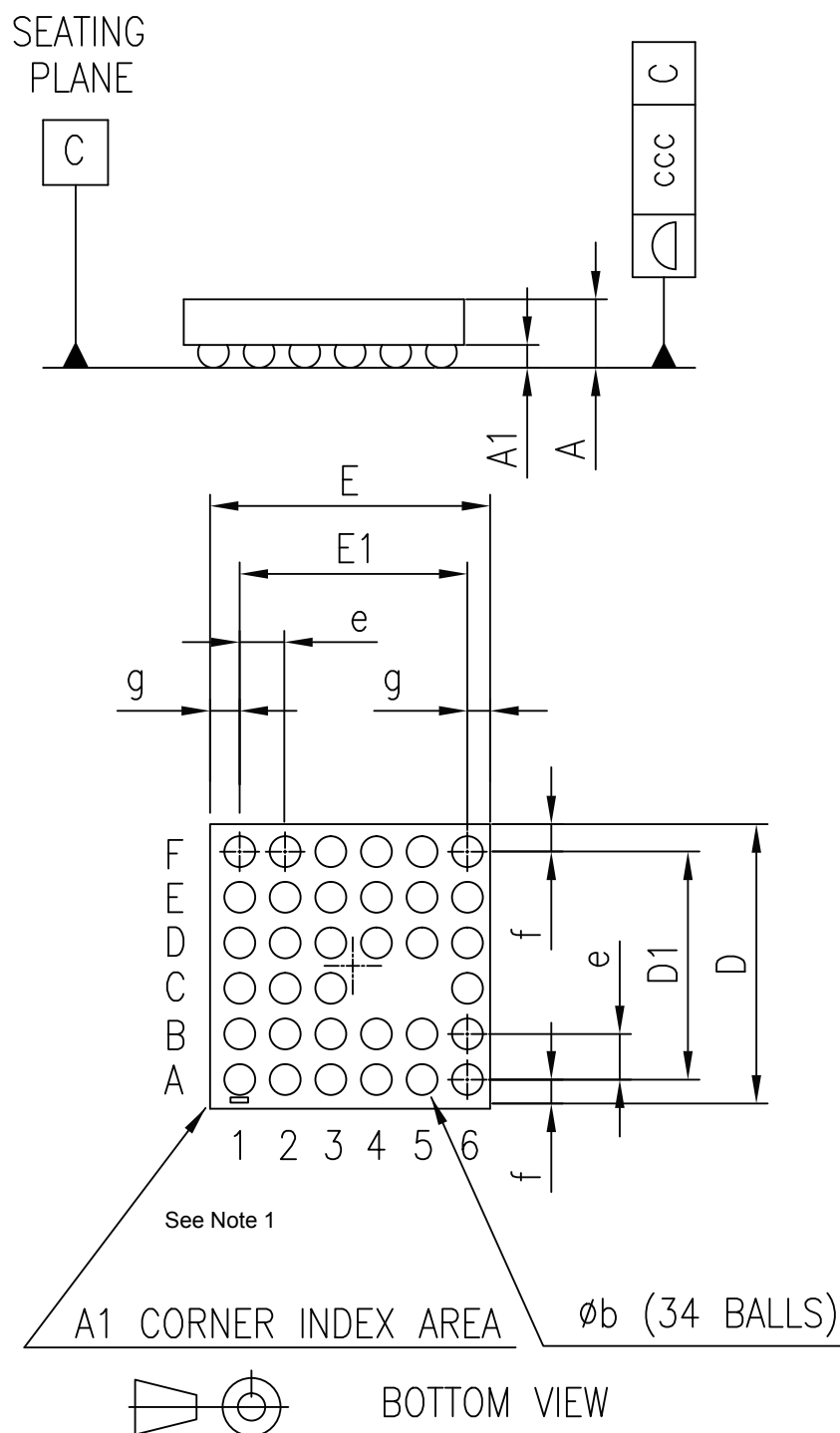
Table 225. QFN48 (|6 x 6 x 0.85 pitch 0.4 mm) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.8	0.85	0.9
A1		0.1	
D	5.9	6	6.1
D1	4.1	4.2	4.3
E	5.9	6	6.1
E1	4.1	4.2	4.3
e		0.4	
F		0.5	
G		0.05	

Dim.	mm		
	Min.	Typ.	Max.
b	0.15	0.2	0.25
L	0.3	0.4	0.5

10.3 WLCSP34 package information

Figure 34. WLCSP34 (2.66 x 2.56 x 0.5 pitch 0.4 mm) package outline



WLCSP34_POA_8165249

1. The corner of terminal A1 must be identified on the top surface by using a laser marking dot.

Table 226. WLCSP34 (2.66 x 2.56 x 0.5 pitch 0.4 mm) mechanical data

Dim.	mm.			Notes
	Min.	Typ.	Max.	
A			0.50	
A1		0.20		
b		0.27		(1)
D	2.50	2.56	2.58	(2)
D1		2.00		
E	2.60	2.66	2.68	(3)
E1		2.00		
e		0.40		
f		0.28		
g		0.33		
ccc			0.05	

1. The typical ball diameter before mounting is 0.25 mm.

2. $D = f + D1 + f$.

3. $E = g + E1 + g$.

11 PCB assembly guidelines

For Flip Chip mounting on the PCB, STMicroelectronics recommends the use of a solder stencil aperture of 330 μm maximum and a typical stencil thickness of 125 μm .

Flip Chips are fully compatible with the use of near eutectic 95.8% Sn, 3.5% Ag, 0.7% Cu solder paste with no-clean flux. ST's recommendations for Flip-Chip board mounting are illustrated on the soldering reflow profile shown in Figure 36. Flip Chip CSP (2.71 x 2.58 x 0.5 pitch 0.4 mm) package reflow profile recommendation.

Figure 35. Flip Chip CSP (2.71 x 2.58 x 0.5 pitch 0.4 mm) package reflow profile recommendation

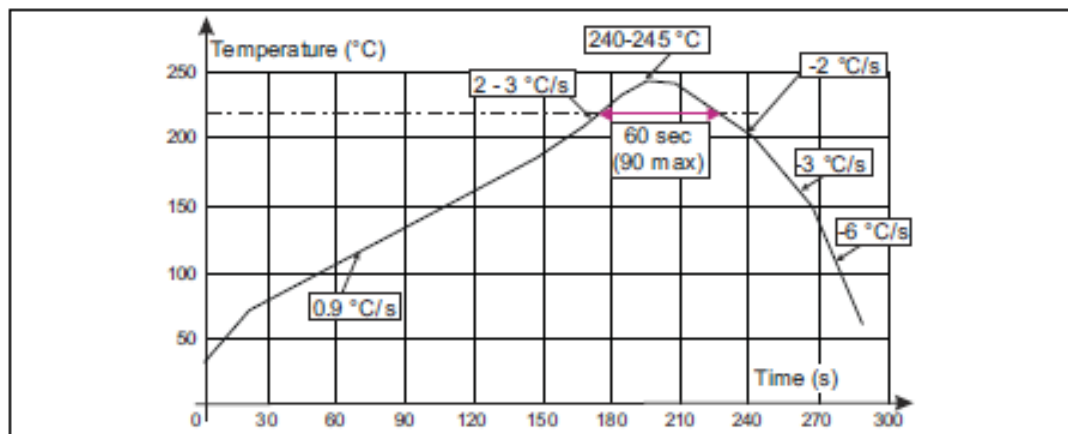


Table 227. Flip Chip CSP (2.71 x 2.58 x 0.5 pitch 0.4 mm) package reflow profile recommendation

Profile	Value	
	Typ.	Max.
Temp. gradient in preheat (T = 70 - 180 °C/s)	0.9 °C/s	3 °C/s
Temp. gradient (T = 200 - 225 °C)	2 °C/s	3 °C/s
Peak temp. in reflow	240 - 245 °C	260 °C
Time above 200 °C	60 s	90 s
Temp. gradient in cooling	-2 to -3 °C	-6 °C/s
Time from 50 to 220 °C	160 to 220 °C	

Dwell time in the soldering zone (with temperature higher than 220 °C) has to be kept as short as possible to prevent component and substrate damage. Peak temperature must not exceed 260 °C. Controlled atmosphere (N₂ or N₂H₂) is recommended during the whole reflow, especially above 150 °C.

Flip Chips are able to withstand three times the previous recommended reflow profile to be compatible with a double reflow when SMDs are mounted on both sides of the PCB plus one additional repair.

A maximum of three soldering reflows are allowed for these lead-free packages (with repair step included).

The use of a no-clean paste is highly recommended to avoid any cleaning operation. To prevent any bump cracks, ultrasonic cleaning methods are not recommended.

12 Ordering information

Table 228. Ordering information

Order code	Package	Packing
BlueNRG-232	QFN32 (5x5 mm)	Tape and reel
BlueNRG-248	QFN48 (6x6 mm)	
BlueNRG-234	WLCSP34	

Revision history

Table 229. Document revision history

Date	Version	Changes
07-Jun-2017	1	Initial release.
16-Nov-2017	2	Updated features in cover page and Section 2 BlueNRG-2 Bluetooth low energy stack.
14-Feb-2018	3	Minor text changes throughout the document.
26-Feb-2018	4	Updated Figure 31. Application circuit: active DC-DC converter QFN32 package with BALFNRG-02D3 balun.
26-Jun-2018	5	Minor text changes throughout the document.
29-Apr-2020	6	Updated Table 207. Memory mapping, Table 16. CKGEN_SOC - CLOCK_EN register description: address offset CKGEN_SOC_BASE_ADDR+0x20, Table 28. Impedance of the ADC pin, Table 31. ADC - CTRL register description: address offset ADC_BASE_ADDR+0x00, Table 130. IO functional map, Table 132. Pin characteristics, Table 153. MFT IO functions, Table 209. Absolute maximum ratings, Table 213. Digital I/O specifications, Table 214. Peripheral current consumption, Table 223. Auxiliary block characteristics. Updated Section 3.3 Memories, Section 3.4.1.2 Active state, Section 3.6.2.4 ADC conversion, Section 3.12.2.2 GPIO characteristics, Section 3.14.2 Functional description, Section 3.15.3 RTC registers Updated Figure 10. ADC block diagram, Figure 21. MFT mode 4 block diagram, Figure 27. Application circuit: non-active DC-DC converter QFN32 package.

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